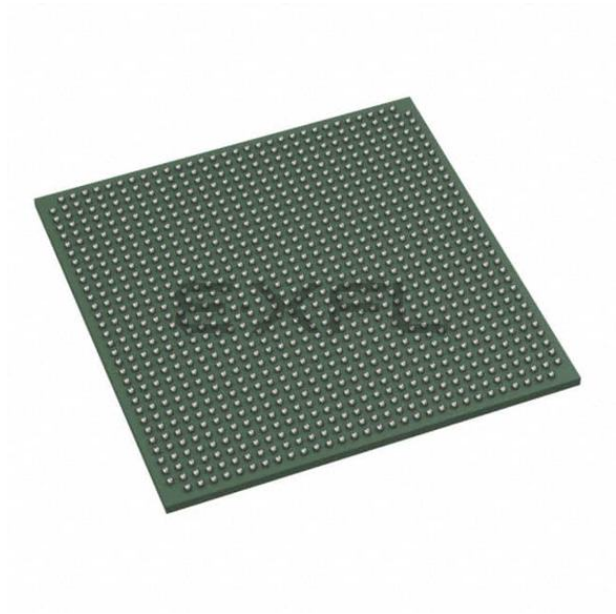
Lattice Semiconductor Corporation - LFSC3GA40E-5FFN1020I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

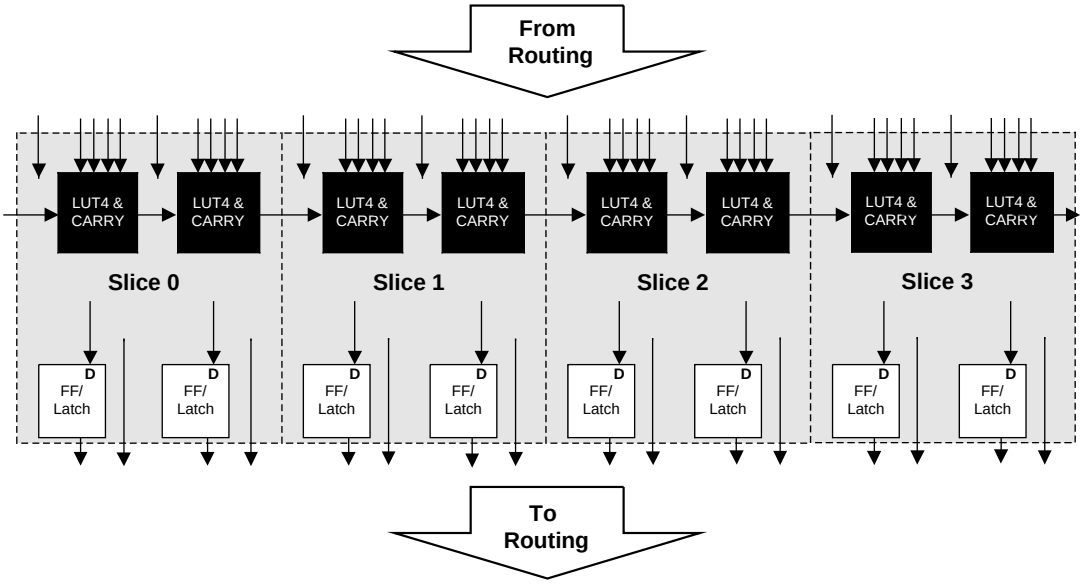
Details	
Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	562
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFCBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga40e-5ffn1020i

PFU Blocks

The core of the LatticeSC devices consists of PFU blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram



Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to implement 5, 6, 7 and 8 Input LUTs (LUT5, LUT6, LUT7 and LUT8). There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

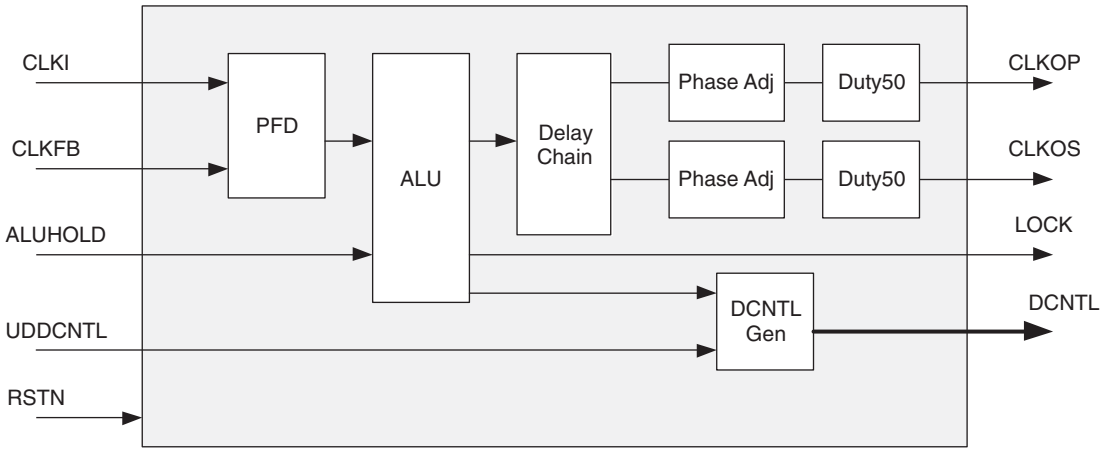
There is a Digital Control (DCNTL) bus available from the DLL block. This Digital Control bus is available to the delay lines in the PIC blocks in the adjacent banks. The UDDCNTL signal allows the user to latch the current value on the digital control bus.

Figure 2-12 shows the DLL block diagram of the DLL inputs and outputs. The output of the phase frequency detector controls an arithmetic logic unit (ALU) to add or subtract one delay tap. The digital output of this ALU is used to control the delay value of the delay chain and this digital code is transmitted via the DCNTL bus.

The sysCLOCK DLL can be configured at power-up, then, if desired, reconfigured dynamically through the Serial Memory Interface bus which interfaces with the on-chip Microprocessor Interface (MPI) bus. In addition, users can drive the SMI interface from routing if desired.

The user can configure the DLL for many common functions such as clock injection match and single delay cell. Lattice provides primitives in its design for time reference delay (DDR memory) and clock injection delay removal.

Figure 2-12. DLL Diagram



PLL/DLL Cascading

The LatticeSC devices have been designed to allow certain combinations of PLL and DLL cascading. The allowable combinations are as follows:

- PLL to PLL
- PLL to DLL
- DLL to DLL
- DLL to PLL

DLLs are used to shift the clock in relation to the data for source synchronous inputs. PLLs are used for frequency synthesis and clock generation for source synchronous interfaces. Cascading PLL and DLL blocks allows applications to utilize the unique benefits of both DLL and PLLs.

When cascading the DLL to the PLL, the DLL can be used to drive the PLL to create fine phase shifts of an input clock signal. Figure 2-13 shows a shift of all outputs for CLKOP and CLKOS out in time.

Figure 2-13. DLL to PLL

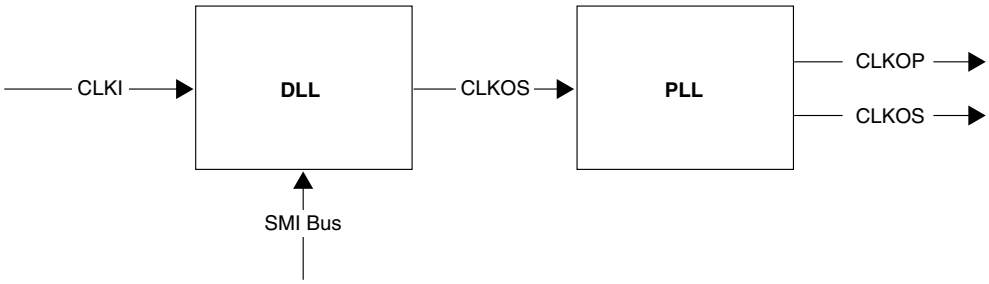


Figure 2-14 shows a shift of only CLKOP out in time.

Figure 2-14. PLL to DLL

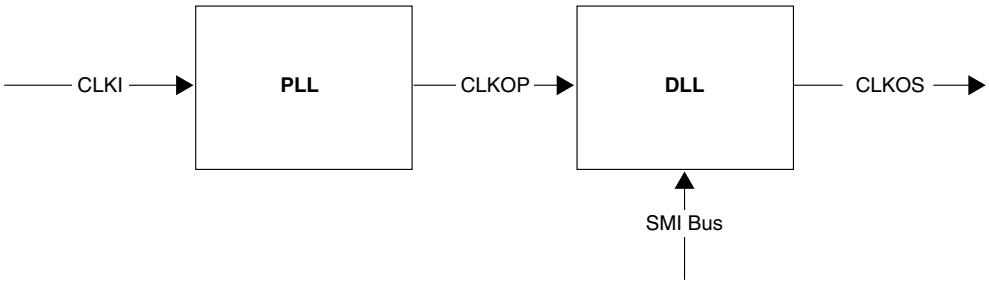
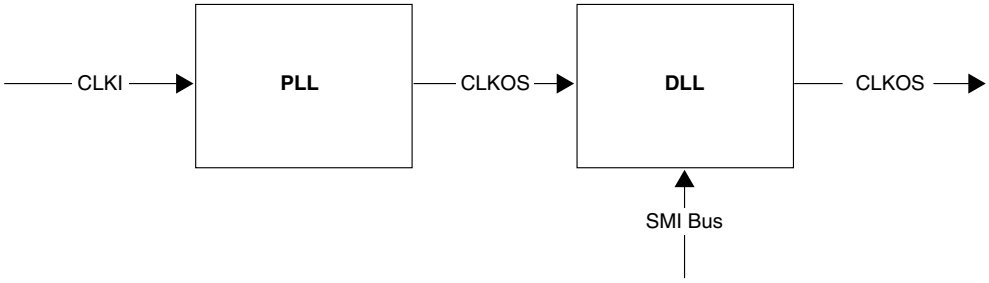


Figure 2-15 shows a shift of only CLKOS out in time.

Figure 2-15. PLL to DLL



For further information on the DLL, please see details of additional technical documentation at the end of this data sheet.

sysMEM Memory Block

The sysMEM block can implement single port, true dual port, pseudo dual port or FIFO memories. Dedicated FIFO support logic allows the LatticeSC devices to efficiently implement FIFOs without consuming LUTs or routing resources for flag generation. Each block can be used in a variety of depths and widths as shown in Table 2-5. Memory with ranges from x1 to x18 in all modes: single port, pseudo-dual port and FIFO also providing x36.

Figure 2-26. LatticeSC Banks

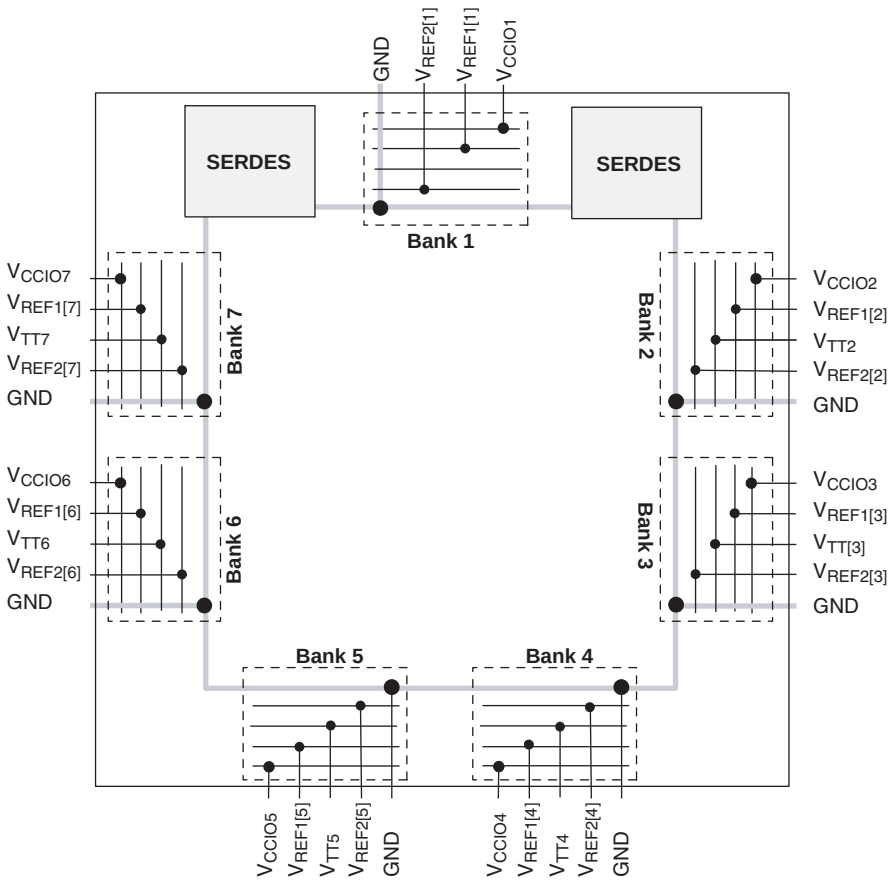


Table 2-7. Maximum Number of I/Os Per Bank in LatticeSC Family

Device	LFSC/M15	LFSC/M25	LFSC/M40	LFSC/M80	LFSC/M115
Bank1	104	80	136	80	136
Bank2	28	36	60	96	136
Bank3	60	84	96	132	156
Bank4	72	100	124	184	208
Bank5	72	100	124	184	208
Bank6	60	84	96	132	156
Bank7	28	36	60	96	136

Note: Not all the I/Os of the Banks are available in all the packages

The LatticeSC devices contain three types of PURESPEED I/O buffers:

1. **Left and Right Sides (Banks 2, 3, 6 and 7)**
   These buffers can support LVCMOS standards up to 2.5V. A differential output driver (for LVDS and RSDS) is provided on all primary PIO pairs (A and B) and differential receivers are available on all pairs. Complimentary drivers are available. Adaptive input logic is available on PIOs A or C.

2. **Top Side (Bank 1)**
   These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but differential drivers for LVDS and RSDS are not available. Adaptive input logic is not available on this side. Complimentary output drivers are available.

Table 2-10. Supported Output Standards[4]

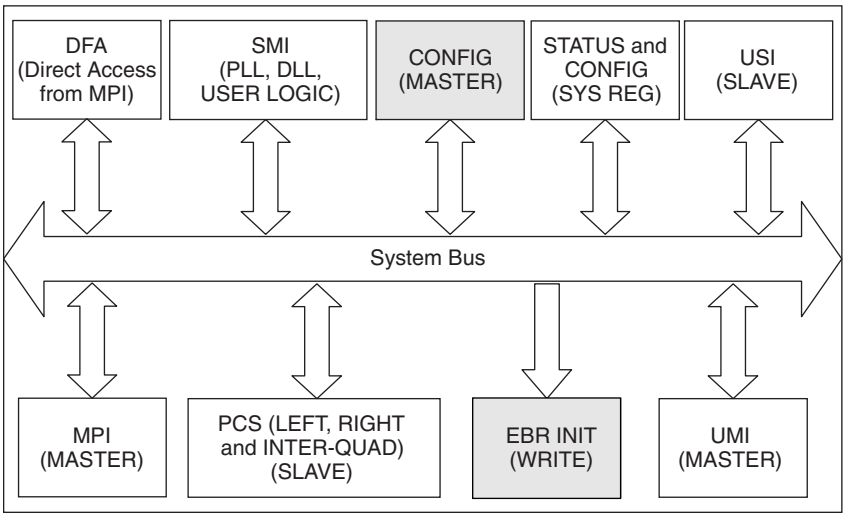
Output Standard	Drive	V_{CCIO} (Nom)	On-chip Output Termination
Single-ended Interfaces			
LVTTL/D[1]	8mA, 16mA, 24mA	3.3	None.
LVCMOS33/D[1]	8mA, 16mA, 24mA	3.3	None
LVCMOS25/D[1, 2]	4mA, 8mA, 12mA, 16mA,	2.5	None, series: 25, 33, 50, 100
LVCMOS18/D[1, 2]	4mA, 8mA, 12mA, 16mA,	1.8	None, series: 25, 33, 50, 100
LVCMOS15/D[1, 2]	4mA, 8mA, 12mA, 16mA,	1.5	None, series: 25, 33, 50, 100
LVCMOS12/D[1, 2]	2mA, 4mA, 8mA, 12mA	1.2	None, series: 25, 33, 50, 100
PCIX15	N/A	1.5	None
PCI33, PCIX33, AGP1X33, AGP2X33	N/A	3.3	None
HSTL18_I	N/A	1.8	None, series: 50
HSTL18_II	N/A	1.8	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
HSTL15_I	N/A	1.5	None, series: 50
HSTL15_II	N/A	1.5	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
SSTL33_I	N/A	3.3	None
SSTL33_II	N/A	3.3	None
SSTL25_I	N/A	2.5	None, series: 50
SSTL25_II	N/A	2.5	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
SSTL18_ I	N/A	1.8	None, series: 33
SSTL18_II	N/A	1.8	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
Differential Interfaces			
SSTL18D_I	N/A	1.8	None, series: 33
SSTL25D_I	N/A	2.5	None, series: 50
SSTL18D_II, SSTL25D_II	N/A	1.2/2.5/3.3	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
SSTL33D_I, II	N/A	3.3	None
HSTL15D_I, HSTL18D_I	N/A	1.5/1.8	None, series: 50
HST15D_II, HSTL18D_II	N/A	1.5/1.8	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
LVDS	2mA, 3.5mA, 4mA, 6mA	N/A	None
Mini-LVDS	3.5mA, 4mA, 6mA	N/A	None
BLVDS25	N/A	N/A	None
MLVDS25	N/A	N/A	None
LVPECL33[3]	N/A	3.3	None
RSDS	2mA, 3.5mA, 4mA, 6mA	N/A	None

1. D refers to open drain capability.
2. User can select either drive current or driver impedances but not both.
3. Emulated with external resistors.
4. No GTL or GTL+ support.

PCI Clamp

A programmable PCI clamp is available on the top and bottom banks of the device. The PCI clamp can be turned “ON” or “OFF” on each pin independently. The PCI clamp is used when implementing a 3.3V PCI interface. The

Figure 2-31. LatticeSC System Bus Interfaces



Several interfaces exist between the System Bus and other FPGA elements. The MPI interface acts as a bridge between the external microprocessor bus and System Bus. The MPI may work in an independent clock domain from the System Bus if the System Bus clock is not sourced from the external microprocessor clock. Pipelined operation allows high-speed memory interface to the EBR and peripheral access without the requirement for additional cycles on the bus. Burst transfers allow optimal use of the memory interface by giving advance information of the nature of the transfers.

Details for the majority of the peripherals can be found in the associated technical documentation, see details at the end of this data sheet. Additional details of the MPI are provided below.

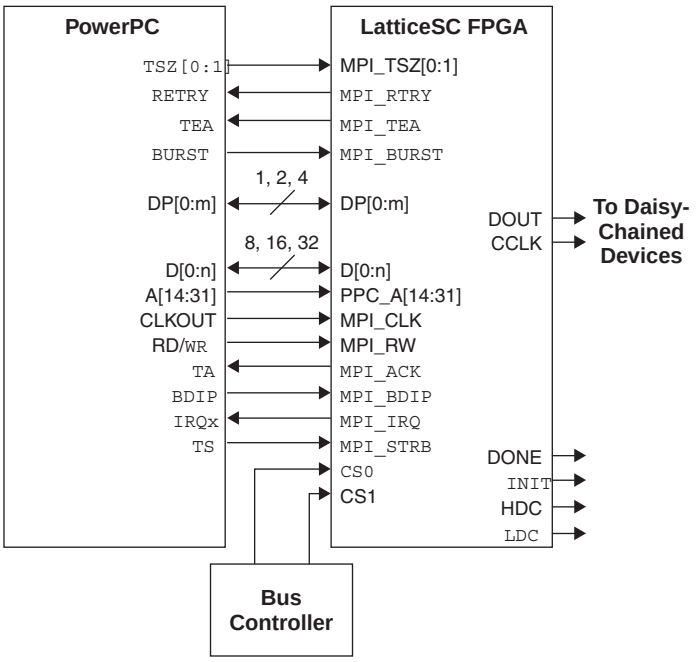
Microprocessor Interface (MPI)

The LatticeSC family devices have a dedicated synchronous MPI function block. The MPI is programmable to operate with PowerPC/PowerQUICC MPC860/MPC8260 series microprocessors. The MPI implements an 8-, 16-, or 32-bit interface with 1-bit, 2-bit, or 4-bit parity to the host processor (PowerPC) that can be used for configuration and read-back of the FPGA as well as for user-defined data processing and general monitoring of FPGA functions.

The control portion of the MPI is available following power-up of the FPGA if the mode pins specify MPI mode, even if the FPGA is not yet configured. The width of the data port is selectable among 8-, 16-, or 32-bit and the parity bus can be 1-, 2-, or 4-bit. In configuration mode the data and parity bus width are related to the state of the M[0:3] mode pins. For post-configuration use, the MPI must be included in the configuration bit stream by using an MPI library element in your design from the ispLEVER primitive library, or by setting the bit of the MPI configuration control register prior to the start of configuration. The user can also enable and disable the parity bus through the configuration bit stream. These pads can be used as general I/O when they are not needed for MPI use.

The MPI block also provides the capability to interface directly to the FPGA fabric with a databus after configuration.The bus protocol is still handled by the MPI block but the direct FPGA access allows high-speed block data transfers such as DMA transactions. Figure 2-32 shows one of the ways a PowerPC is connected to MPI.

Figure 2-32. PowerPCI and MPI Schematic



Configuration and Testing

The following section describes the configuration and testing features of the LatticeSC family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeSC devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS33, 25 and 18 standards. For additional detail refer to technical information at the end of the data sheet.

Device Configuration

All LatticeSC devices contain three possible ports that can be used for device configuration. The serial port, which supports bit-wide configuration, and the sysCONFIG port that supports both byte-wide and serial configuration. The MPI port supports 8-bit, 16-bit or 32-bit configuration.

The serial port supports both the IEEE Std. 1149.1 Boundary Scan specification and the IEEE Std. 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six of the I/Os used as dedicated pins and the rest being dual-use pins. When sysCONFIG mode is not used, these dual-use pins are available for general purpose I/O. All I/Os for the sysCONFIG and MPI ports are in I/O bank #1.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port. Once a configuration port is selected, that port is locked and another configuration port cannot be activated until the next re-initialization sequence. For additional detail refer to technical information at the end of the data sheet.

Internal Logic Analyzer Capability (ispTRACY)

All LatticeSC devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time. For additional detail refer to technical information at the end of the data sheet.

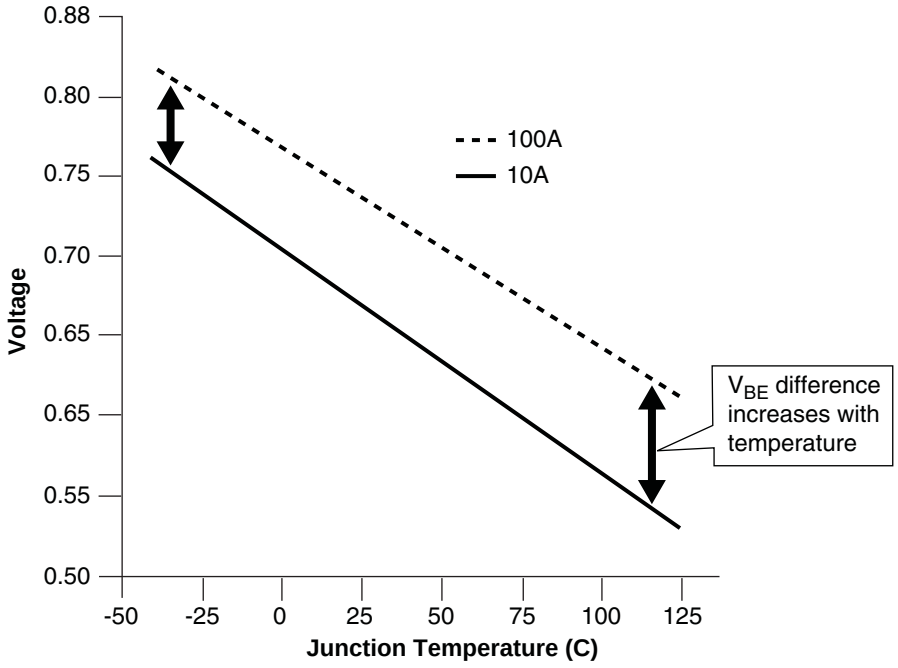
Temperature Sensing

Lattice provides a way to monitor the die temperature by using a temperature-sensing diode that is designed into every LatticeSC device. The difference in V_{BE} of the diode at two different forward currents varies with temperature. This relationship is shown in Figure 2-33. The accuracy of the temperature-sensing diode is typically +/- 10°C.

On packages that include PROBE_GND, the most accurate measurements will occur between the TEMP pin and the PROBE_GND pin. On packages that do not include PROBE_GND, measurements should be made between the TEMP pin and board ground.

This temperature-sensing diode is designed to work with an external temperature sensor such as the Maxim 1617A. The Maxim 1617A is configured to measure difference in V_{BE} (of the temperature-sensing diode) at 10µA and at 100µA. This difference in V_{BE} voltage varies with temperature at approximately 1.64 mV/°C. A typical device with a 85°C junction temperature will measure approximately 593mV. For additional detail refer to TN1115, Temperature Sensing Diode in LatticeSC Devices.

Figure 2-33. Sensing Diode Typical Characteristics



Oscillator

Every LatticeSC device has an internal CMOS oscillator, which is used as a master serial clock for configuration and is also available as a potential general purpose clock (MCK) for the FPGA core. There is a K divider (divide by 2/4/8/16/32/64/128) available with this oscillator to get lower MCK frequencies. This clock is available as a general purpose clock signal to the software routing tool. For additional detail refer to technical information at the end of the data sheet.

LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
GTLPLUS15	GTLPLUS15	-0.013	-0.017	0.012	0.004	0.037	0.024	ns
GTL12	GTL12	-0.063	-0.071	-0.007	-0.048	0.056	-0.032	ns
Output Adjusters								
LVDS	LVDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
RSDS	RSDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
BLVDS25	BLVDS	-0.129	0.05	-0.136	0.069	-0.136	0.083	ns
MLVDS25	MLVDS	-0.059	0.059	-0.057	0.096	-0.054	0.133	ns
LVPECL33	LVPECL	-0.334	-0.181	-0.325	-1.389	-0.315	-2.598	ns
HSTL18_I	HSTL_18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18_II	HSTL_18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL18D_I	Differential HSTL 18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18D_II	Differential HSTL 18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL15_I	HSTL_15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15_II	HSTL_15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
HSTL15D_I	Differential HSTL 15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15D_II	Differential HSTL 15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
SSTL33_I	SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33_II	SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL33D_I	Differential SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33D_II	Differential SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL25_I	SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25_II	SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL25D_I	Differential SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25D_II	Differential SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL18_I	SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18_II	SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
SSTL18D_I	Differential SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18D_II	Differential SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
LVTTL33_8mA	LVTTL 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVTTL33_16mA	LVTTL 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVTTL33_24mA	LVTTL 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVCMOS33_24mA	LVCMOS 3.3 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	-0.174	0.004	-0.195	0.002	-0.215	0	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0	0	0	0	0	0	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.094	-0.025	0.107	0.096	0.12	0.216	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.145	-0.054	0.162	0.063	0.181	0.179	ns
LVCMOS25_OD	LVCMOS 2.5 open drain	0.073	-0.125	0.081	-0.081	0.091	-0.09	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	-0.278	-0.099	-0.312	-0.115	-0.345	-0.131	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	-0.073	-0.078	-0.078	-0.084	-0.083	-0.089	ns

LatticeSC/M Internal Timing Parameters[1] (Continued)

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
EBR Timing									
t_{CO_EBR}	CK_Q_DEL	Clock (Read) to output from Address or Data	—	1.900	—	2.116	—	2.335	ns
t_{COO_EBR}	CK_Q_DEL	Clock (Write) to output from EBR output Register	0.390	—	0.444	—	0.498	—	ns
t_{SUDATA_EBR}	D_CK_SET	Setup Data to EBR Memory (Write clk)	-0.173	—	-0.192	—	-0.210	—	ns
t_{HDATA_EBR}	D_CK_HLD	Hold Data to EBR Memory (Write clk)	0.276	—	0.305	—	0.335	—	ns
t_{SUADDR_EBR}	A_CK_SET	Setup Address to EBR Memory (Write clk)	-0.165	—	-0.182	—	-0.200	—	ns
t_{HADDR_EBR}	A_CK_HLD	Hold Address to EBR Memory (Write clk)	0.269	—	0.298	—	0.327	—	ns
t_{SUWREN_EBR}	CE_CK_SET	Setup Write/Read Enable to EBR Memory (Write/Read clk)	0.225	—	0.226	—	0.226	—	ns
t_{HWREN_EBR}	CE_CK_HLD	Hold Write/Read Enable to EBR Memory (write/read clk)	0.073	—	0.095	—	0.116	—	ns
t_{SUCE_EBR}	CS_CK_SET	Clock Enable Setup Time to EBR Output Register (Read clk)	0.261	—	0.269	—	0.276	—	ns
t_{HCE_EBR}	CS_CK_HLD	Clock Enable Hold Time to EBR Output Register (Read clk)	0.023	—	0.039	—	0.055	—	ns
t_{RSTO_EBR}	RESET_Q_DEL	Reset To Output Delay Time from EBR Output Register (asynchronous)	—	0.589	—	0.673	—	0.757	ns
Cycle Boosting Timing									
t_{DEL1}	DEL1	Cycle boosting delay 1 applies to PIO, PFU, EBR	—	0.480	—	0.524	—	0.570	ns
t_{DEL2}	DEL2	Cycle boosting delay 2 applies to PIO, PFU, EBR	—	0.922	—	1.005	—	1.090	ns
t_{DEL3}	DEL3	Cycle boosting delay 3 applies to PIO, PFU, EBR	—	1.366	—	1.488	—	1.612	ns

1. Complete timing parameters for a user design will be incorporated when running ispLEVER. This is a sampling of the key timing parameters.

Figure 3-8. Read Mode with Input and Output Registers

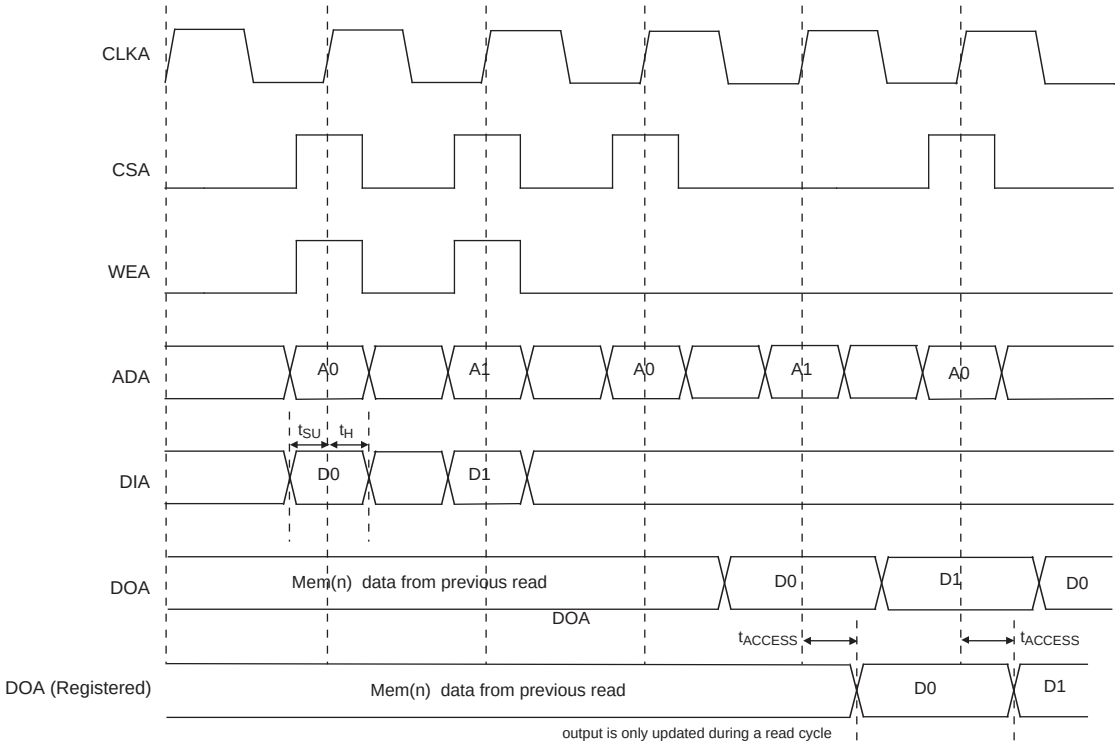
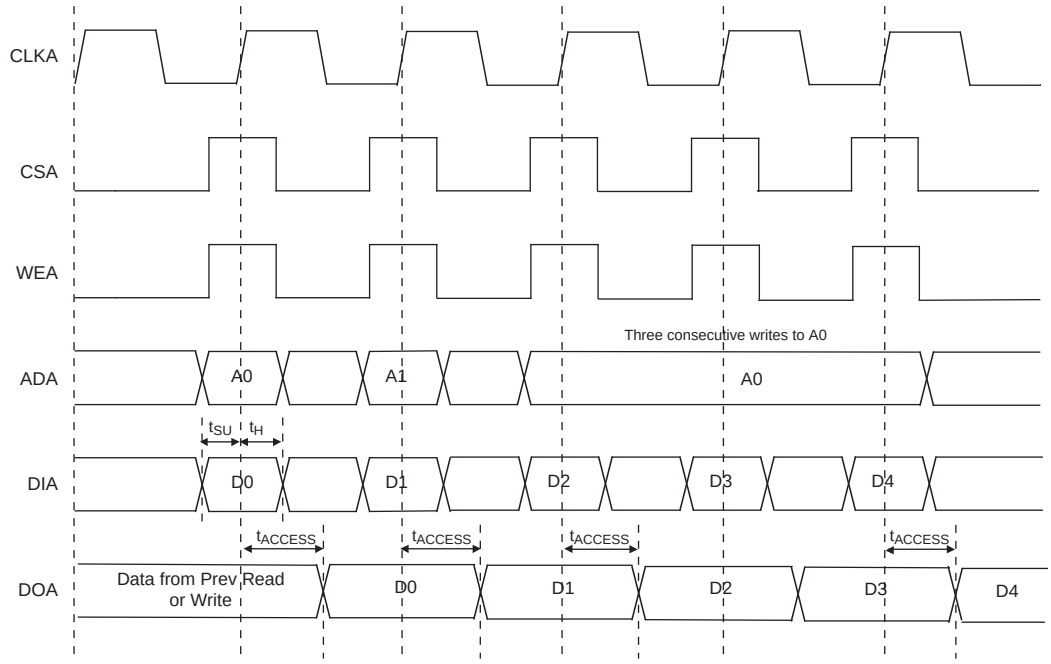


Figure 3-9. Write Through (SP Read/Write On Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
A29	RESP_URC	-		RESP_URC	-	
D26	VCC12	-		VCC12	-	
C30	A_REFCLKN_R	-		A_REFCLKN_R	-	
B30	A_REFCLKP_R	-		A_REFCLKP_R	-	
F24	A_VDDAX25_R	-		A_VDDAX25_R	-	
D25	VCC12	-		VCC12	-	
C28	A_VDDIB0_R	-		A_VDDIB0_R	-	
B28	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B27	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E25	VCC12	-		VCC12	-	
A28	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
C27	A_VDDOB0_R	-		A_VDDOB0_R	-	
A27	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C26	A_VDDOB1_R	-		A_VDDOB1_R	-	
A26	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
D24	VCC12	-		VCC12	-	
A25	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B26	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
B25	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
E24	VCC12	-		VCC12	-	
C25	A_VDDIB1_R	-		A_VDDIB1_R	-	
D23	VCC12	-		VCC12	-	
C24	A_VDDIB2_R	-		A_VDDIB2_R	-	
B24	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B23	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E23	VCC12	-		VCC12	-	
A24	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
C23	A_VDDOB2_R	-		A_VDDOB2_R	-	
A23	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
C22	A_VDDOB3_R	-		A_VDDOB3_R	-	
A22	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
D22	VCC12	-		VCC12	-	
A21	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B22	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
B21	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
E22	VCC12	-		VCC12	-	
C21	A_VDDIB3_R	-		A_VDDIB3_R	-	
G22	PT43D	1	HDC/SI	PT49D	1	HDC/SI
F22	PT43C	1	LDCN/SCS	PT49C	1	LDCN/SCS
B20	PT41B	1	D8/MPI_DATA8	PT49B	1	D8/MPI_DATA8
B19	PT41A	1	CS1/MPI_CS1	PT49A	1	CS1/MPI_CS1
A20	PT40D	1	D9/MPI_DATA9	PT47D	1	D9/MPI_DATA9
A19	PT40C	1	D10/MPI_DATA10	PT47C	1	D10/MPI_DATA10
D19	PT39B	1	CS0N/MPI_CS0N	PT47B	1	CS0N/MPI_CS0N
D18	PT39A	1	RDN/MPI_STRB_N	PT47A	1	RDN/MPI_STRB_N

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G1	NC	-		PL20B	7	
M4	NC	-		NC	-	
J3	NC	-		NC	-	
P5	NC	-		NC	-	
W5	NC	-		PL48C	6	
T6	NC	-		PL35C	6	
U3	NC	-		PL36A	6	
V3	NC	-		PL36B	6	
T5	NC	-		PL39A	6	
T4	NC	-		PL39B	6	
V5	NC	-		PL43C	6	
U6	NC	-		PL42C	6	
U4	NC	-		PL40A	6	
U5	NC	-		PL40B	6	
V4	NC	-		PL43D	6	
Y2	NC	-		PL47A	6	
AA2	NC	-		PL47B	6	
W3	NC	-		PL47D	6	
Y3	NC	-		PL47C	6	
AB3	NC	-		NC	-	
AC4	NC	-		PL53A	6	
AD4	NC	-		PL53B	6	
AE3	NC	-		PL56A	6	
AF3	NC	-		PL56B	6	
AF7	NC	-		PB7A	5	
AF6	NC	-		PB7B	5	
AH4	NC	-		PB8A	5	
AG5	NC	-		PB8B	5	
AF8	NC	-		PB9A	5	
AG8	NC	-		PB9B	5	
AG7	NC	-		NC	-	
AG10	NC	-		NC	-	
AF12	NC	-		NC	-	
AH7	NC	-		PB15A	5	
AE13	NC	-		PB15D	5	
AG13	NC	-		PB23C	5	
AH8	NC	-		PB15B	5	
AJ5	NC	-		PB17A	5	
AJ6	NC	-		PB17B	5	
AF15	NC	-		PB21D	5	
AJ7	NC	-		PB19A	5	
AJ8	NC	-		PB19B	5	
AE12	NC	-		PB15C	5	
AF16	NC	-		PB38D	4	
AF19	NC	-		PB49D	4	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V25	PL44C	6		PL56C	6	
W25	PL44D	6		PL56D	6	
U34	PL45A	6		PL57A	6	
V34	PL45B	6		PL57B	6	
V26	PL45C	6		PL57C	6	
W26	PL45D	6		PL57D	6	
V33	PL47A	6		PL60A	6	
W33	PL47B	6		PL60B	6	
V24	PL47C	6		PL60C	6	
W24	PL47D	6		PL60D	6	
W31	PL48A	6		PL63A	6	
Y31	PL48B	6		PL63B	6	
Y29	PL48C	6		PL63C	6	
AA29	PL48D	6		PL63D	6	
Y33	PL49A	6		PL65A	6	
AA33	PL49B	6		PL65B	6	
Y28	PL49C	6		PL65C	6	
AA28	PL49D	6		PL65D	6	
AB32	PL51A	6		PL76A	6	
AC32	PL51B	6		PL76B	6	
AA26	PL51C	6		PL76C	6	
AA27	PL51D	6	DIFFR_6	PL76D	6	DIFFR_6
AB31	PL52A	6		PL77A	6	
AC31	PL52B	6		PL77B	6	
Y24	PL52C	6		PL77C	6	
AA24	PL52D	6		PL77D	6	
AE34	PL53A	6		PL78A	6	
AF34	PL53B	6		PL78B	6	
AB30	PL53C	6		PL78C	6	
AC30	PL53D	6		PL78D	6	
AD33	PL56A	6		PL80A	6	
AE33	PL56B	6		PL80B	6	
AD30	PL56C	6		PL80C	6	
AE30	PL56D	6		PL80D	6	
AE32	PL57A	6		PL81A	6	
AF32	PL57B	6		PL81B	6	
AA25	PL57C	6		PL81C	6	
AB25	PL57D	6		PL81D	6	
AJ34	PL58A	6		PL82A	6	
AK34	PL58B	6		PL82B	6	
AB27	PL58C	6		PL82C	6	
AC27	PL58D	6		PL82D	6	
AF33	PL60A	6		PL84A	6	
AG33	PL60B	6		PL84B	6	
AC29	PL60C	6		PL84C	6	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG18	PB42C	5		PB61C	5	
AF18	PB42D	5		PB61D	5	
AP19	PB43A	5		PB63A	5	
AP18	PB43B	5		PB63B	5	
AJ18	PB43C	5		PB63C	5	
AH18	PB43D	5		PB63D	5	
AP17	PB45A	4		PB65A	4	
AP16	PB45B	4		PB65B	4	
AJ17	PB45C	4		PB65C	4	
AH17	PB45D	4		PB65D	4	
AN17	PB46A	4		PB66A	4	
AN16	PB46B	4		PB66B	4	
AE17	PB46C	4		PB66C	4	
AD17	PB46D	4		PB66D	4	
AK17	PB47A	4		PB67A	4	
AK16	PB47B	4		PB67B	4	
AG17	PB47C	4		PB67C	4	
AF17	PB47D	4		PB67D	4	
AM16	PB49A	4		PB69A	4	
AM15	PB49B	4		PB69B	4	
AJ15	PB49C	4		PB69C	4	
AJ14	PB49D	4		PB69D	4	
AL16	PB50A	4		PB70A	4	
AL15	PB50B	4		PB70B	4	
AG16	PB50C	4		PB70C	4	
AF16	PB50D	4		PB70D	4	
AP15	PB51A	4		PB71A	4	
AP14	PB51B	4		PB71B	4	
AH15	PB51C	4		PB71C	4	
AH14	PB51D	4		PB71D	4	
AN15	PB53A	4	PCLKT4_2	PB74A	4	PCLKT4_2
AN14	PB53B	4	PCLKC4_2	PB74B	4	PCLKC4_2
AE16	PB53C	4	PCLKT4_7	PB74C	4	PCLKT4_7
AD16	PB53D	4	PCLKC4_7	PB74D	4	PCLKC4_7
AK15	PB54A	4	PCLKT4_1	PB75A	4	PCLKT4_1
AK14	PB54B	4	PCLKC4_1	PB75B	4	PCLKC4_1
AG15	PB54C	4	PCLKT4_6	PB75C	4	PCLKT4_6
AG14	PB54D	4	PCLKC4_6	PB75D	4	PCLKC4_6
AM13	PB55A	4	PCLKT4_0	PB77A	4	PCLKT4_0
AM12	PB55B	4	PCLKC4_0	PB77B	4	PCLKC4_0
AJ12	PB55C	4	VREF2_4	PB77C	4	VREF2_4
AJ11	PB55D	4		PB77D	4	
AL13	PB57A	4	PCLKT4_5	PB79A	4	PCLKT4_5
AL12	PB57B	4	PCLKC4_5	PB79B	4	PCLKC4_5
AH12	PB57C	4		PB79C	4	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
H34	PL40B	7	
M32	PL53A	7	
N32	PL53B	7	
P28	PL53C	7	
R28	PL53D	7	
J34	PL55A	7	
K34	PL55B	7	
P30	PL55C	7	
R30	PL55D	7	
W34	PL73A	6	
Y34	PL73B	6	
W32	PL75A	6	
Y32	PL75B	6	
AA34	PL78A	6	
AB34	PL78B	6	
AC34	PL81A	6	
AD34	PL81B	6	
Y30	PL82A	6	
AA30	PL82B	6	
AB33	PL83A	6	
AC33	PL83B	6	
AC2	PR83B	3	
AB2	PR83A	3	
AA5	PR82B	3	
Y5	PR82A	3	
AD1	PR81B	3	
AC1	PR81A	3	
AB1	PR78B	3	
AA1	PR78A	3	
Y3	PR75B	3	
W3	PR75A	3	
Y1	PR73B	3	
W1	PR73A	3	
R5	PR55D	2	
P5	PR55C	2	
K1	PR55B	2	
J1	PR55A	2	
R7	PR53D	2	
P7	PR53C	2	
N3	PR53B	2	
M3	PR53A	2	
H1	PR40B	2	
G1	PR40A	2	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AD33	PL59D	6		PL73D	6	
AA38	PL60A	6		PL74A	6	
AB38	PL60B	6		PL74B	6	
AC29	PL60C	6		PL74C	6	
AD29	PL60D	6		PL74D	6	
AA41	PL61A	6		PL75A	6	
AB41	PL61B	6		PL75B	6	
AC34	PL61C	6		PL75C	6	
AD34	PL61D	6		PL75D	6	
AA42	PL63A	6		PL77A	6	
AB42	PL63B	6		PL77B	6	
AC37	PL63C	6		PL77C	6	
AD37	PL63D	6		PL77D	6	
AC38	PL64A	6		PL78A	6	
AD38	PL64B	6		PL78B	6	
AD36	PL64C	6		PL78C	6	
AE36	PL64D	6		PL78D	6	
AC39	PL65A	6		PL79A	6	
AD39	PL65B	6		PL79B	6	
AD35	PL65C	6		PL79C	6	
AE35	PL65D	6		PL79D	6	
AC40	PL67A	6		PL81A	6	
AD40	PL67B	6		PL81B	6	
AE37	PL67C	6		PL81C	6	
AF37	PL67D	6		PL81D	6	
AC41	PL68A	6		PL82A	6	
AD41	PL68B	6		PL82B	6	
AE34	PL68C	6		PL82C	6	
AF34	PL68D	6		PL82D	6	
AC42	PL69A	6		PL83A	6	
AD42	PL69B	6		PL83B	6	
AE33	PL69C	6		PL83C	6	
AF33	PL69D	6		PL83D	6	
AE38	PL72A	6		PL86A	6	
AF38	PL72B	6		PL86B	6	
AE32	PL72C	6		PL86C	6	
AF32	PL72D	6		PL86D	6	
AE41	PL73A	6		PL87A	6	
AF41	PL73B	6		PL87B	6	
AE31	PL73C	6		PL87C	6	
AF31	PL73D	6		PL87D	6	
AE42	PL74A	6		PL88A	6	
AF42	PL74B	6		PL88B	6	
AG37	PL74C	6		PL88C	6	
AH37	PL74D	6		PL88D	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AY41	PB12A	5		PB13A	5	
BA41	PB12B	5		PB13B	5	
AT39	PB12C	5		PB13C	5	
AT38	PB12D	5		PB13D	5	
AV37	PB13A	5		PB15A	5	
AV36	PB13B	5		PB15B	5	
AM31	PB13C	5		PB15C	5	
AM32	PB13D	5		PB15D	5	
BA40	PB15A	5		PB16A	5	
BB40	PB15B	5		PB16B	5	
AM29	PB15C	5		PB16C	5	
AL29	PB15D	5		PB16D	5	
AY39	PB16A	5		PB17A	5	
AY38	PB16B	5		PB17B	5	
AN33	PB16C	5		PB17C	5	
AN32	PB16D	5		PB17D	5	
BA39	PB17A	5		PB19A	5	
BA38	PB17B	5		PB19B	5	
AT37	PB17C	5		PB19C	5	
AT36	PB17D	5		PB19D	5	
AW36	PB19A	5		PB20A	5	
AW35	PB19B	5		PB20B	5	
AM28	PB19C	5		PB20C	5	
AL28	PB19D	5		PB20D	5	
BB38	PB20A	5		PB21A	5	
BB39	PB20B	5		PB21B	5	
AR34	PB20C	5		PB21C	5	
AR33	PB20D	5		PB21D	5	
AV35	PB21A	5		PB23A	5	
AV34	PB21B	5		PB23B	5	
AT33	PB21C	5		PB23C	5	
AT34	PB21D	5		PB23D	5	
BA37	PB23A	5		PB25A	5	
BA36	PB23B	5		PB25B	5	
AP33	PB23C	5		PB25C	5	
AP32	PB23D	5		PB25D	5	
AY36	PB24A	5		PB26A	5	
AY35	PB24B	5		PB26B	5	
AN31	PB24C	5		PB26C	5	
AN30	PB24D	5		PB26D	5	
BB37	PB25A	5		PB27A	5	
BB36	PB25B	5		PB27B	5	
AP31	PB25C	5		PB27C	5	
AP30	PB25D	5		PB27D	5	
AV33	PB27A	5		PB29A	5	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AW25	VCCIO5	-		VCCIO5	-	
AW31	VCCIO5	-		VCCIO5	-	
AW37	VCCIO5	-		VCCIO5	-	
AY22	VCCIO5	-		VCCIO5	-	
AY28	VCCIO5	-		VCCIO5	-	
AY34	VCCIO5	-		VCCIO5	-	
AB39	VCCIO6	-		VCCIO6	-	
AC36	VCCIO6	-		VCCIO6	-	
AD32	VCCIO6	-		VCCIO6	-	
AE40	VCCIO6	-		VCCIO6	-	
AF35	VCCIO6	-		VCCIO6	-	
AG31	VCCIO6	-		VCCIO6	-	
AH39	VCCIO6	-		VCCIO6	-	
AJ36	VCCIO6	-		VCCIO6	-	
AK32	VCCIO6	-		VCCIO6	-	
AL40	VCCIO6	-		VCCIO6	-	
AM35	VCCIO6	-		VCCIO6	-	
AP39	VCCIO6	-		VCCIO6	-	
AR36	VCCIO6	-		VCCIO6	-	
AU40	VCCIO6	-		VCCIO6	-	
AA40	VCCIO7	-		VCCIO7	-	
H36	VCCIO7	-		VCCIO7	-	
J40	VCCIO7	-		VCCIO7	-	
L35	VCCIO7	-		VCCIO7	-	
M39	VCCIO7	-		VCCIO7	-	
P36	VCCIO7	-		VCCIO7	-	
R40	VCCIO7	-		VCCIO7	-	
T31	VCCIO7	-		VCCIO7	-	
U35	VCCIO7	-		VCCIO7	-	
V39	VCCIO7	-		VCCIO7	-	
W32	VCCIO7	-		VCCIO7	-	
Y36	VCCIO7	-		VCCIO7	-	
AA14	VTT_2	2		VTT_2	2	
AA15	VTT_2	2		VTT_2	2	
R12	VTT_2	2		VTT_2	2	
V14	VTT_2	2		VTT_2	2	
AB14	VTT_3	3		VTT_3	3	
AB15	VTT_3	3		VTT_3	3	
AE14	VTT_3	3		VTT_3	3	
AJ13	VTT_3	3		VTT_3	3	
AH21	VTT_4	4		VTT_4	4	
AJ18	VTT_4	4		VTT_4	4	
AJ19	VTT_4	4		VTT_4	4	
AJ20	VTT_4	4		VTT_4	4	
AJ21	VTT_4	4		VTT_4	4	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.